

RF power transistor from the LdmoST family of n-channel enhancement-mode lateral MOSFETs

Datasheet - production data



life.augmented





Features

- Excellent thermal stability
- Common source configuration
- P_{OUT} (@28 V) = 45 W with 16 dB gain @ 1600 MHz
- BeO free package
- In compliance with the 2002/95/EC European directive

Description

The LET16045C is a common source N-channel enhancement-mode lateral field-effect RF power transistor designed for broadband commercial and industrial applications at frequencies up to 1.6 GHz. The LET16045C is designed for high gain and broadband performance operating in common source mode at 28 V. It is ideal for INMARSAT satellite communications.

Table 1. Device summary

Order code	Package	Branding
LET16045C	M243	LET16045C

This is information on a product in full production.

Maximum ratings 1

Table 2. Absolute maximum ratings (T _{CASE} = 25 °C)				
Symbol	Parameter	Value	Unit	
V _{(BR)DSS}	Drain-source voltage	80	V	
V _{GS}	Gate-source voltage	-0.5 to +15	V	
۱ _D	Drain current	9	А	
P _{DISS}	Power dissipation (@ $T_C = 70 \ ^{\circ}C$)	100	W	
Τ _J	Max. operating junction temperature	200	°C	
T _{STG}	Storage temperature	-65 to +150	°C	

able 2.	Absolute	maximum	ratings	(T _{CASE}	= 25 °C))
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Table 3. Thermal data

Symbol	Parameter	Value	Unit
R _{th(JC)}	Junction-case thermal resistance	1.3	°C/W



2 Electrical characteristics

T_C = 25 °C

Symbol	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	$V_{GS} = 0 \text{ V}; \text{ I}_{DS} = 10 \text{ mA}$	80			V
I _{DSS}	$V_{GS} = 0 V; V_{DS} = 28 V$			1	μΑ
I _{GSS}	$V_{GS} = 20 \text{ V}; V_{DS} = 0 \text{ V}$			1	μΑ
V _{GS(Q)}	V _{DS} = 28 V; I _D = 300 mA	2.0		5.0	V
V _{DS(ON)}	V _{GS} = 10 V; I _D = 3 A			1.1	V
G_{FS}	V _{DS} = 10 V; I _D = 3 A	2.5			mho
C _{ISS}	V _{GS} = 0 V; V _{DS} = 28 V; f = 1 MHz		58		pF
C _{OSS}	$V_{GS} = 0 V; V_{DS} = 28 V; f = 1 MHz$		29		pF
C _{RSS}	V _{GS} = 0 V; V _{DS} = 28 V; f = 1 MHz		0.8		pF

Table 4. Static

Table 5. Dynamic

Symbol	Test conditions	Min.	Тур.	Max.	Unit
P _{OUT}	$V_{DD} = 28 \text{ V}; \text{ I}_{DQ} = 400 \text{ mA}; \text{ P}_{IN} = 2 \text{ W}$	45	54		W
G _{PS}	V _{DD} = 28 V; I _{DQ} = 400 mA; P _{OUT} = 45 W	15	16		dB
h _D	V_{DD} = 28 V; I _{DQ} = 400 mA; P _{OUT} = 45 W	50	55	-	%
Load mismatch	V_{DD} = 28 V; I_{DQ} = 400 mA; P_{OUT} = 50 W; f = 1600 MHz All phase angles		20:1		VSWR

Table 6. Impedance data

Frequency (MHz)	Z source (Ω)	Z load (Ω)
1600	1.1 - j1.6	1.1 - j0.6



3 Typical performances



Figure 2. Gain and efficiency vs output power Figure 3. Gain vs ouptut power and bias current

Figure 4. Ouptut power vs drain supply voltage





4 Board layout, schematic and BOM



Figure 5. Board layout

Figure 6. Schematic





ltem	Qty	Part number	Vendor	Description
R1	1	CR1206-8W-561JB	VENKEL	560 OHM, 1/8W surface mount chip resistor
R2	1	CR1206-8W-132JB	VENKEL	1.3K OHM, 1/8W surface mount chip resistor
R3	1	CR1206-8W-100JB	VENKEL	10 OHM, 1/8W surface mount chip resistor
FB1,2,3,4,	4	2743021447	FAIR-RITE CORP	Surface Mount EMI sheild bead
C1,C4,C5,C6	4		JOHANSON	0.6-4.5pF giga trim variable capacitor
C2,C7,C9,C12	4	ATC100B470XXXX	ATC	47 pF chip capacitor
C3	1	27291PC	JOHANSON	0.8-8pF giga trim variable capacitor
C8	1	ATC100B330XXXX	ATC	33pF chip capacitor
C10	1			330uF, 50V electrolytic capacitor
C11	1			10uF, 63V electrolytic capacitor
C13	1			100uF, 63V electrolytic capacitor
L1, L2	2	1812SMS-33NJ	Coilcraft	33 nH coil
TL1, TL2	2			L= 1.350in [34.29mm] W=0.082in [2.080mm]
TL3	1			L= 0.469in [11.91mm] W=0.080in [2.020mm]
TL4, TL5	2			L= 0.277in [7.03mm] W=0.323in [8.210mm]
TL6	1			L= 0.207in [5.26mm] W=0.506in [12.85mm]
TL7	1			L= 0.208in [5.28mm] W=0.506in [12.85mm]
TL8,TL9	2			L= 0.275in [6.98mm] W=0.324in [8.230mm]
TL10,TL11	2			L= 0.470in [11.93mm] W=0.080in [2.020mm]
TL12	1			L= 1.351in [34.33mm] W=0.082in [2.080mm]
Board 3X5	1		Rogers Corp	Er=2.55 t=0.0026in h=0.030in

Table 7. Component list



5 Package mechanical data

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Figure 7. M243 package dimensions

Table 8. M243	(.230 x .360 2L	N/HERM W/FLG) mechanical data
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Dim.		mm			inch	
	Min.	Тур	Max.	Min.	Тур	Max.
А	5.21		5.72	0.205		0.225
В	5.46		6.48	0.215		0.255
С	5.59		6.1	0.22		0.24
D		14.27			0.562	
E	20.07		20.57	0.79		0.81
F	8.89		9.4	0.35		0.37
G	0.1		0.15	0.004		0.006
Н	3.18		4.45	0.125		0.175
Ι	1.83		2.24	0.072		0.088
J	1.27		1.78	0.05		0.07



6 Revision history

Date	Revision	Changes
14-Sep-2011	1	Initial release.
04-Nov-2011	2	Updated Table 3: Thermal data, Table 4: Static, Table 5: Dynamic and Figure 3: Gain vs ouptut power and bias current. Inserted Table 6: Impedance data and Figure 2: Gain and efficiency vs output power and Figure 4: Ouptut power vs drain supply voltage.
29-Apr-2014	3	Added Section 4: Board layout, schematic and BOM.

Table 9. Document revision history



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DocID022224 Rev 3